

## Features

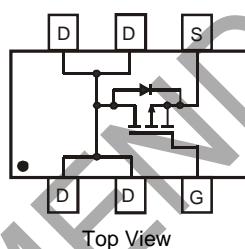
- Low  $R_{DS(ON)}$ :  
40m $\Omega$  @  $V_{GS} = -4.5V$   
70m $\Omega$  @  $V_{GS} = -2.5V$
- Low Input/Output Leakage
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

## Mechanical Data

- Case: SOT26
- Case Material – Molded Plastic. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Solderable per MIL-STD-202, Method 208 (e3)
- Terminal Connections: See Diagram
- Weight: 0.008 grams (Approximate)



Top View

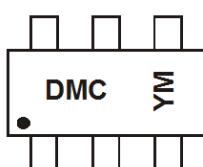
Top View  
Internal Schematic

## Ordering Information (Note 5)

Part Number	Case	Packaging
DMP2066LDM-7	SOT26	3000/Tape & Reel
DMP2066LDMQ-7	SOT26	3000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to <https://www.diodes.com/quality/>.
  5. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

## Marking Information



DMC = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: F = 2018)  
 M = Month (ex: 9 = September)

### Date Code Key

Year	2008	2009	2010	2011	~	2018	2019	2020				
Code	V	W	X	Y	~	F	G	H				
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Maximum Ratings** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	$V_{DSS}$	-20	V
Gate-Source Voltage	$V_{GSS}$	$\pm 12$	V
Drain Current (Note 6) Continuous	$T_A = +25^\circ\text{C}$	$I_D$	-4.6
	$T_A = +70^\circ\text{C}$		-3.7
Pulsed Drain Current (Note 7)	$I_{DM}$	-18	A
Body-Diode Continuous Current (Note 6)	$I_S$	2.0	A

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 6)	$P_D$	1.25	W
Thermal Resistance, Junction to Ambient (Note 6); Steady-State	$R_{\theta JA}$	100	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

**Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>STATIC PARAMETERS</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	-20	—	—	V	$I_D = -250\mu\text{A}, V_{GS} = 0\text{V}$
Zero Gate Voltage Drain Current	$I_{DSS}$	—	—	-1	$\mu\text{A}$	$V_{DS} = -20\text{V}, V_{GS} = 0\text{V}$
Gate-Body Leakage Current	$I_{GSS}$	—	—	$\pm 100$	nA	$V_{DS} = 0\text{V}, V_{GS} = \pm 12\text{V}$
Gate Threshold Voltage	$V_{GS(TH)}$	-0.6	-0.96	-1.2	V	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$
On State Drain Current (Note 8)	$I_{D(ON)}$	-15	—	—	A	$V_{GS} = -4.5\text{V}, V_{DS} = -5\text{V}$
Static Drain-Source On-Resistance (Note 8)	$R_{DS(ON)}$	—	29 55	40 70	$\text{m}\Omega$	$V_{GS} = -4.5\text{V}, I_D = -4.6\text{A}$ $V_{GS} = -2.5\text{V}, I_D = -3.8\text{A}$
Forward Transconductance (Note 8)	$g_{FS}$	—	9	—	S	$V_{DS} = -10\text{V}, I_D = -4.6\text{A}$
Diode Forward Voltage (Note 8)	$V_{SD}$	-0.5	-0.72	-1.4	V	$I_S = -2.1\text{A}, V_{GS} = 0\text{V}$
Maximum Body-Diode Continuous Current (Note 6)	$I_S$	—	—	-1.7	A	—
<b>DYNAMIC PARAMETERS (Note 9)</b>						
Input Capacitance	$C_{iss}$	—	820	—	$\text{pF}$	$V_{DS} = -15\text{V}, V_{GS} = 0\text{V}$ $f = 1.0\text{MHz}$
Output Capacitance	$C_{oss}$	—	200	—	$\text{pF}$	
Reverse Transfer Capacitance	$C_{rss}$	—	160	—	$\text{pF}$	$V_{DS} = 0\text{V}, V_{GS} = 0\text{V}$ $f = 1.0\text{MHz}$
Gate Resistance	$R_G$	—	2.5	—	$\Omega$	
<b>SWITCHING CHARACTERISTICS</b>						
Total Gate Charge	$Q_G$	—	10.1	—	nC	$V_{DS} = -10\text{V}, V_{GS} = -4.5\text{V}, I_D = -4.5\text{A}$
Gate-Source Charge	$Q_{GS}$	—	1.5	—		
Gate-Drain Charge	$Q_{GD}$	—	4.3	—		
Turn-On Delay Time	$t_{D(ON)}$	—	4.4	—	ns	$V_{DS} = -10\text{V}, V_{GS} = -4.5\text{V}, I_D = -1\text{A}, R_G = 6.0\Omega$
Rise Time	$t_R$	—	9.9	—		
Turn-Off Delay Time	$t_{D(OFF)}$	—	28.0	—		
Fall Time	$t_F$	—	23.4	—		

- Notes:
6. Device mounted on 1"x1", FR-4 PC board with 2 oz. Copper and test pulse width  $t \leq 10\text{s}$ .
  7. Repetitive Rating, pulse width limited by junction temperature.
  8. Test pulse width  $t = 300\mu\text{s}$ .
  9. Guaranteed by design. Not subject to production testing.

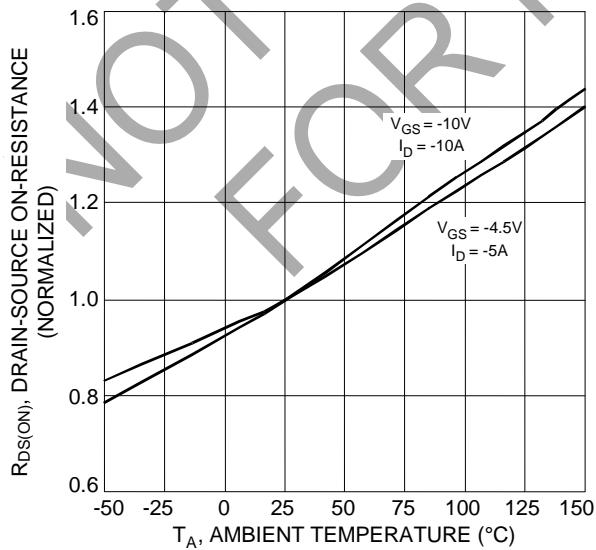
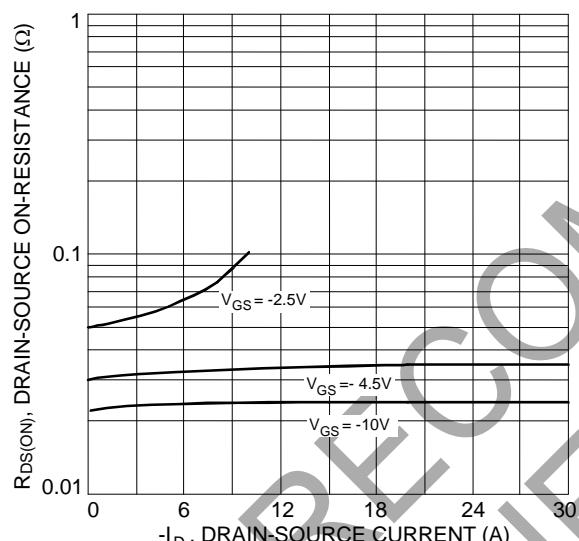
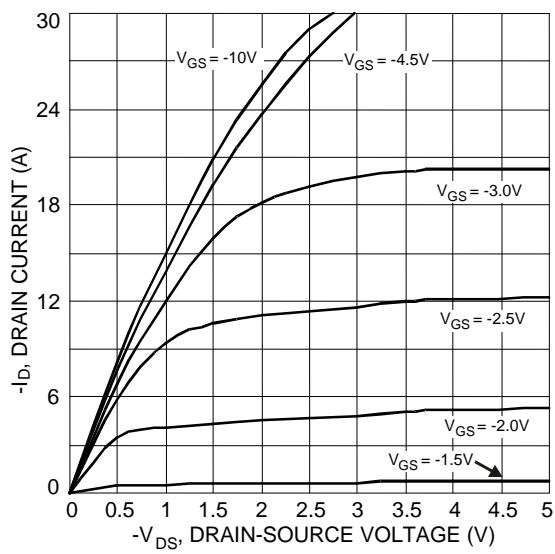
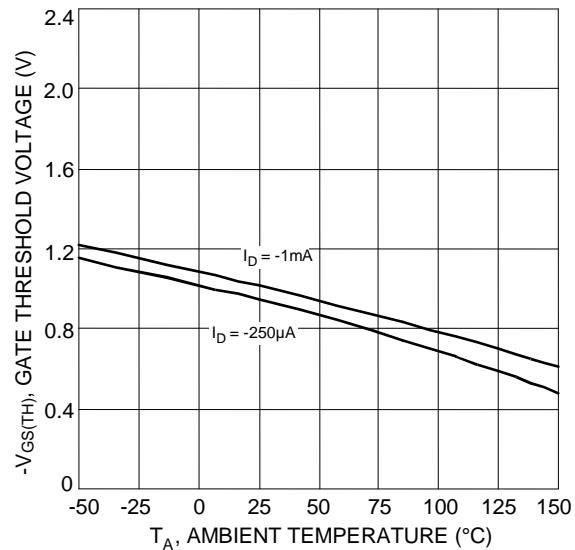
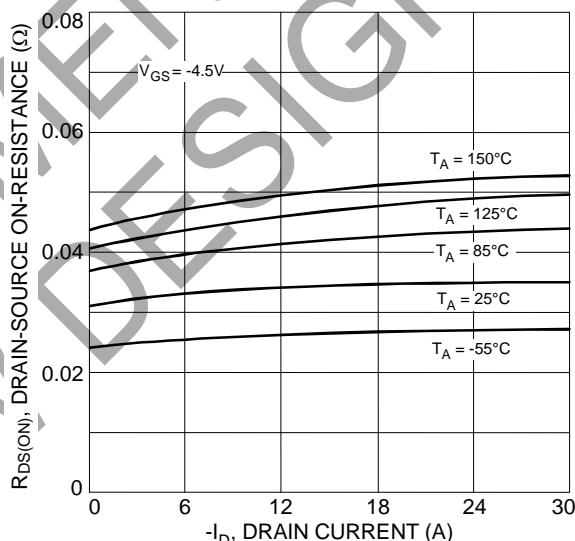
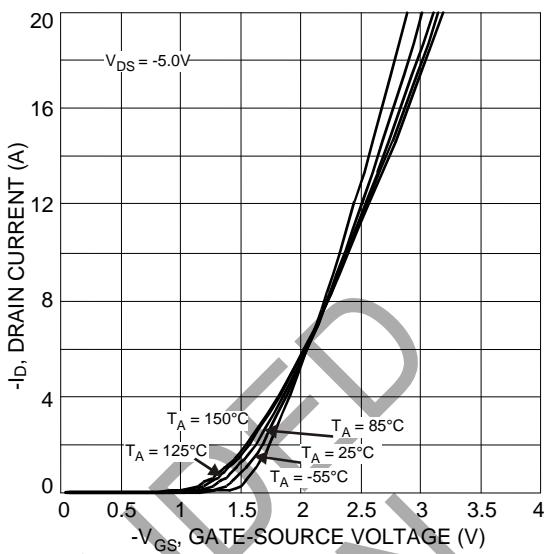


Fig. 5 Normalized On-Resistance vs. Ambient Temperature



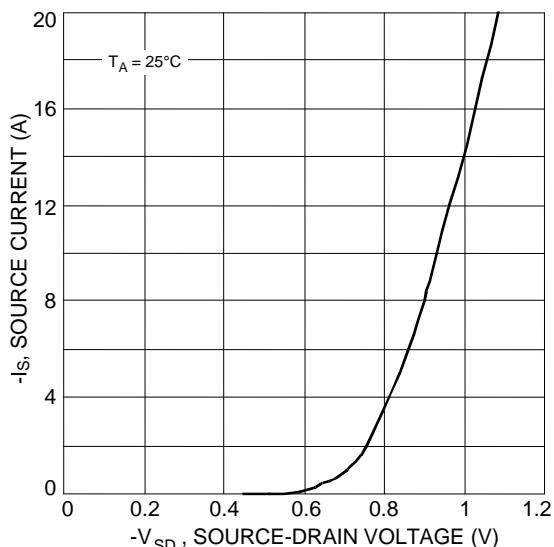


Fig. 7 Diode Forward Voltage vs. Current

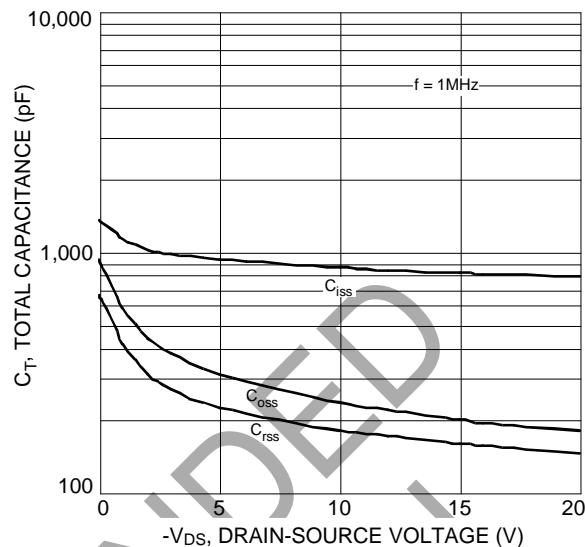


Fig. 8 Typical Total Capacitance

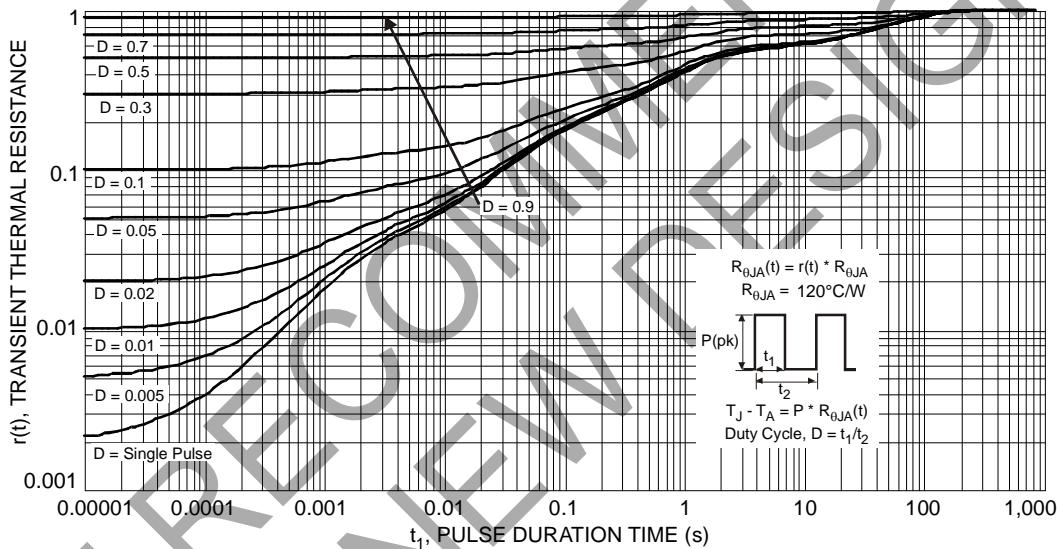


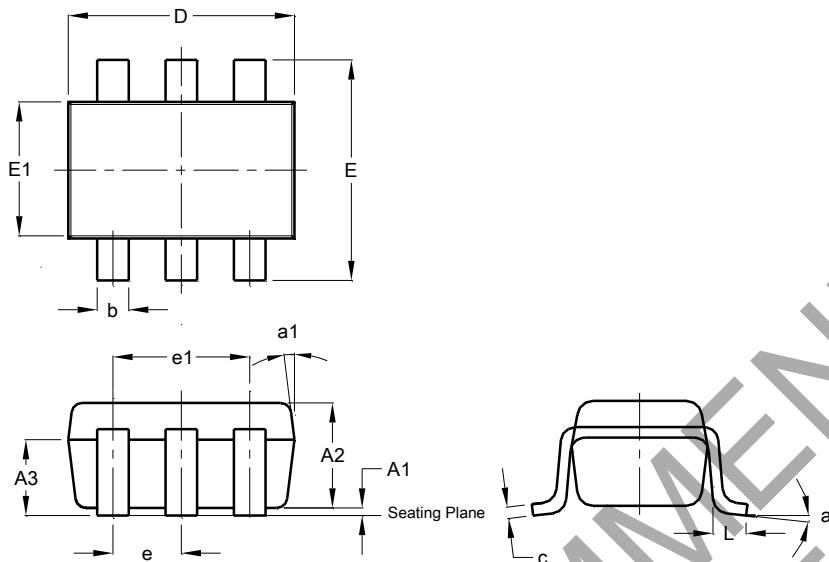
Fig. 9 Transient Thermal Response

NOT RECOMMENDED FOR NEW DESIGN

## Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT26



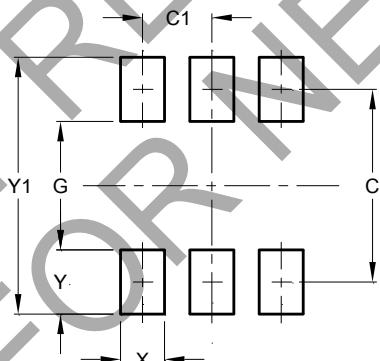
SOT26			
Dim	Min	Max	Typ
<b>A1</b>	0.013	0.10	0.05
<b>A2</b>	1.00	1.30	1.10
<b>A3</b>	0.70	0.80	0.75
<b>b</b>	0.35	0.50	0.38
<b>c</b>	0.10	0.20	0.15
<b>D</b>	2.90	3.10	3.00
<b>e</b>	-	-	0.95
<b>e1</b>	-	-	1.90
<b>E</b>	2.70	3.00	2.80
<b>E1</b>	1.50	1.70	1.60
<b>L</b>	0.35	0.55	0.40
<b>a</b>	-	-	8°
<b>a1</b>	-	-	7°

All Dimensions in mm

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT26



Dimensions	Value (in mm)
<b>C</b>	2.40
<b>C1</b>	0.95
<b>G</b>	1.60
<b>X</b>	0.55
<b>Y</b>	0.80
<b>Y1</b>	3.20

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